

Material Content Data Sheet

Sales Product Name	IM06B30AC1	**Issued**	04. September 2024
MA#	MA006039858		
Package	PG-MDIP-24-81	**Weight:**	6961.72 mg

Construction Element	Material group	Materials	CAS if applicable	Weight [mg]	Average mass [%]	Sum [%]	Average mass [ppm]	Sum [ppm]
chip_01	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_02	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_03	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_04	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_05	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_06	inorganic material	silicon	7440-21-3	1.855	0.03	0.03	266	266
chip_07	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_08	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_09	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_10	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_11	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_12	inorganic material	silicon	7440-21-3	0.847	0.01	0.01	122	122
chip_13	inorganic material	silicon	7440-21-3	3.460	0.05	0.05	497	497
leadframe	inorganic material	phosphorus	7723-14-0	0.739	0.01		106	
	non noble metal	iron	7439-89-6	2.465	0.04		354	
	non noble metal	copper	7440-50-8	2461.315	35.35	35.40	353550	354010
wire	noble metal	gold	7440-57-5	0.507	0.01		73	
	non noble metal	aluminium	7429-90-5	50.285	0.72	0.73	7223	7296
encapsulation	organic material	carbon black	1333-86-4	8.250	0.12		1185	
	miscellaneous	miscellaneous	-	20.625	0.30		2963	
	inorganic material	boehmite	1318-23-6	164.998	2.37		23701	
	organic material	phenol formaldehyde resin	9003-35-4	169.123	2.43		24293	
	plastics	phenyl glycidyl ether/ dicyclopentadiene	119345-05-0	169.123	2.43		24293	
	plastics	epoxy resin	29690-82-2	251.622	3.61		36144	
	inorganic material	silicondioxide	14808-60-7	3341.215	47.99	59.25	479940	592519
leadfinish	non noble metal	tin	7440-31-5	44.511	0.64	0.64	6394	6394
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.183			26	27
solder	non noble metal	antimony	7440-36-0	0.257			37	
	noble metal	silver	7440-22-4	0.643	0.01		92	
	non noble metal	tin	7440-31-5	1.671	0.02	0.03	240	369
glue	inorganic material	silicondioxide	60676-86-0	0.309			44	

	plastics	epoxy resin	-	0.464	0.01		67	
	plastics	acrylic resin	-	0.579	0.01		83	
	plastics	maleimide resin	-	0.579	0.01		83	
	noble metal	silver	7440-22-4	1.736	0.02	0.05	249	526
smd	inorganic material	silicondioxide	60676-86-0	0.003			1	
	noble metal	gold	7440-57-5	0.012			2	
	noble metal	palladium	7440-05-3	0.019			3	
	organic material	ethyl cellulose	9004-57-3	0.024			3	
	noble metal	silver	7440-22-4	0.030			4	
	organic material	DEGBE	112-34-5	0.105			15	
	inorganic material	cobalt(II)oxide	1307-96-6	0.200			29	
	inorganic material	copperoxide	1317-38-0	0.576	0.01		83	
	inorganic material	manganesedioxide	1313-13-9	0.658	0.01	0.02	95	235
pcb metal	non noble metal	copper	7440-50-8	12.931	0.19	0.19	1857	1857
pcb plastic	plastics	epoxy resin	-	105.493	1.52		15153	
	inorganic material	glass fibre wool	65997-17-3	128.936	1.85	3.37	18521	33674
pcb plating	noble metal	gold	7440-57-5	0.040			6	
	non noble metal	nickel	7440-02-0	1.827	0.03	0.03	262	268
deviation	< 10%				Sum in total:	100.00		1000000

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